Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP Pavilion x2 Detachable PC</th>
</tr>
</thead>
<tbody>
<tr>
<td>HP Pavilion x2 Detachable</td>
</tr>
<tr>
<td>HP Pavilion x2 Detachable 12</td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries RTC,Battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#)
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble the slate & docking ass'y
2. Remove battery cable from connector on MB
3. Disassemble bezel ass'y from A-cover ass'y
4. Remove LCD cable with touch glass control board
5. Release SPK L&R screw *4 pcs
6. Remove speaker L&R
7. Release slate pogo connector screw *2 pcs
8. Release pogo cable connector on MB
9. Remove the pogo cable & RTC battery
10. Release battery screw *4 pcs
11. Remove battery pack
12. Release ssd screw *1 pcs
13. Remove ssd card
14. Release antenna connector *2
15. Release antenna board screw *1 pcs
16. Remove antenna board
17. Release power & audio & usb ffc connector on MB
18. Release camera cable connector on MB
19. Release MB screw *6 pcs
20. Release MG bracket *1 pcs
21. Remove Mother Board
22. Release MG bracket screw *3 pcs
23. Remove MG bracket
24. Release audio board screw *3 pcs
25. Remove audio bracket
26. Release ffc connector on audio board
27. Remove audio bord
28. Remove audio and usb ffc
29. Release ffc connector on vol. board
30. Release vol. board screw *2 pcs
31. Remove vol.board
32. Remove vol. fcc
33. Release ffc connector on power board
34. Release power board screw *1 pcs
35. Remove power board
36. Remove power fcc
37. Release camera cable connector on camera module

PSG instructions for this template are available at EL-MF877-01
38. Remove camera cable
39. Remove camera module
40. Remove antenna cable
41. Remove base rubber
42. Release base screw *4 pcs
43. Remove base mylar *2 pcs
44. Release base screw *2 pcs
45. Disassemble the base cover from docking ass'y
46. Release docking pogo cable connecter *2 pcs from docking DB
47. Release the KB membrane from docking DB
48. Release ffc connecter on docking DB & TP module
49. Remove TP module ffc
50. Release docking DB screw *2 pcs
51. Remove docking DB
52. Release TP bracket screw *3 pcs
53. Remove TP bracket
54. Release TP holder screw *3 pcs
55. Remove TP ass'y
56. Remove TP mylar
57. Remove TP module
58. Release hinge bracket L&R screw *4 pcs
59. Disassemble the hinge bar ass'y from top ass'y
60. Disassemble the hinge bar bezel from hinge bar cover ass'y
61. Release docking pogo cable connecter screw *2 pcs
62. Remove docking pogo cable
63. Release hinge L&R screw *4 pcs
64. Remove hinge L&R from hinge bar cover ass'y
65. END

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly

3.22 Remove battery module
3.23 Remove service door

3.24 LCD module set disassembly

3.25 Top case disassembly

3.26 Thermal module and mother board disassembly

3.27 Bottom case disassembly